

Elephantech

**Making the world sustainable with
new manufacturing technologies**



**Elephantech Inc. is a startup
that manufactures and sells P-Flex®
a Flexible PCB manufactured
by inkjet printing and copper plating.**

P-Flex® is a Flex PCB manufactured with Pure Additive™ processing, a technology that inkjet-prints silver nano ink onto the required areas of the board surface and forms copper layer by highspeed electroless plating on top.

About Elephantech's manufacturing method (Pure Additive™ processing)

This manufacturing method consists of inkjet-printing silver nano-ink onto the substrate before electroless copper plating is applied to form the circuit. By reducing the amount of metal, liquid waste and man-hours, we can lessen manufacturing costs and shorten the lead time.

(* Patent No. 6300213)

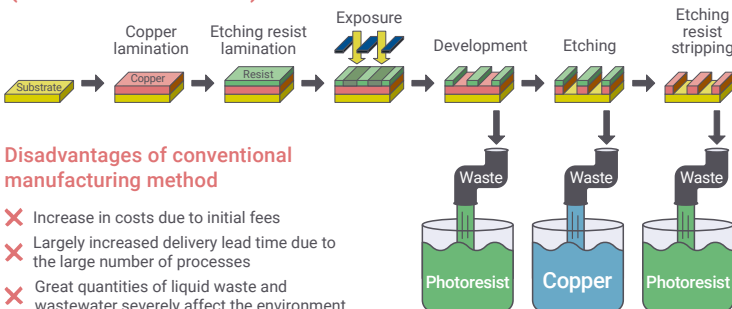
Elephantech's manufacturing method (Pure Additive™ processing)



Advantages of Elephantech's manufacturing method

- ✓ Forming the circuit only where needed allows for a reduction in manufacturing cost and environmental footprint.
- ✓ A simple manufacturing process allowing for a shorter lead time.

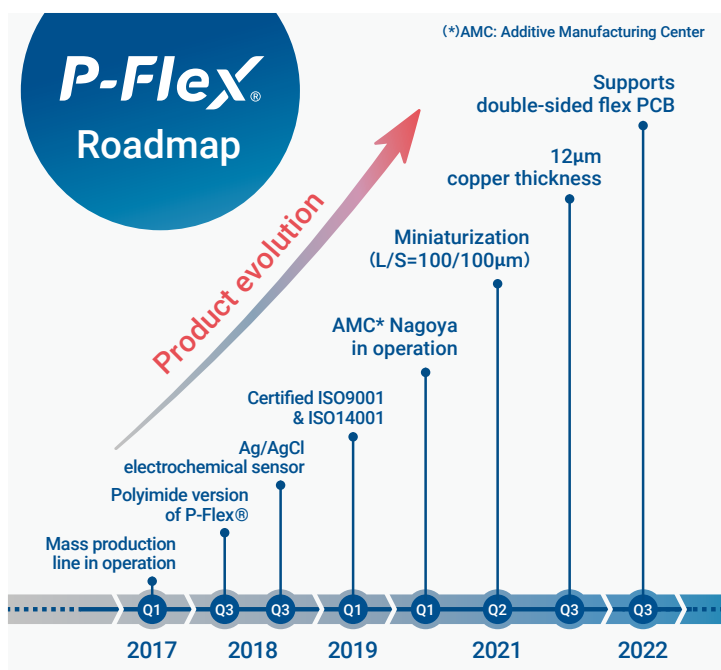
Conventional manufacturing method (subtractive method)



Disadvantages of conventional manufacturing method

- ✗ Increase in costs due to initial fees
- ✗ Largely increased delivery lead time due to the large number of processes
- ✗ Great quantities of liquid waste and wastewater severely affect the environment

P-Flex® Roadmap



P-Flex® Applications

- ✓ Automobile
- ✓ Manufacturing Equipment
- ✓ Home Appliances
- ✓ Office Equipment
- ✓ Food Processing Machinery
- ✓ Medical Equipment
- ✓ Mobile Equipment
- ✓ Wearable Equipment
- ✓ RFID
- ✓ Aerospace Parts

Flexible PCBs are increasingly being adopted to replace existing rigid boards and wiring harnesses in order to reduce weight, miniaturize, and reduce the number of parts. P-Flex®, a new idea and next generation flexible board that is compatible with mass customization is being used even in places where flexible boards could not be used before.



Management Team

Co-founder & CEO, Board Member Shinya Shimizu
 Master of electronics and information engineering, Graduate School of Information Science and Technology, University of Tokyo
 2012: Joined McKinsey & Company and provided consultancy service mainly to manufacturers in Japan.
 January 2014: Co-founded AgIC Inc. and became CEO.

Co-founder & SVP, Board Member Masaaki Sugimoto
 M.S., Earth and Planetary Science, Graduate School of Science, University of Tokyo
 Coursework completed without obtaining a degree, doctorate program, Graduate School of System Design and Management, Keio University
 January 2014: Co-founded AgIC Inc. and became Board Member and Vice President.

Executive Officer & CTO	Junji Takeo	
Executive Officer & CFO	Gosuke Hashimoto	
Non-executive Director	Tomihisa Kamada	Founder and CEO, TomyK Ltd./Co-Founder and former CEO, ACCESS Co., Ltd.
Non-executive Director	Tsuyoshi Ito	Managing Partner, Beyond Next Ventures
Non-executive Director	Shinji Ohshige	Managing Director, Innovation Network Corporation of Japan
Non-executive Auditor	Kengo Ueha	Partner, Beyond Next Ventures

Company Locations



Head office (Hatchobori, Chuo-ku, Tokyo)



AMC Nagoya: Mass production & testing (Nagoya-shi, Aichi)

Company Overview



Elephantech

Elephantech Inc. (Formerly AgIC Inc.*)

*Changed corporate name on September 4, 2017

Establishment January 6, 2014
 Head office 4-3-8 Hatchobori, Chuo-ku, Tokyo 104-0032, Japan
 AMC Nagoya c/o Mitsui Chemicals Inc. Nagoya Works, 2-1 Tangodori, Minami-ku, Nagoya-shi, Aichi 457-0801, Japan
 Capital JPY100 million
 Representative Shinya Shimizu, CEO
 Website <https://www.elephantech.co.jp/en/>
 Contact <https://www.elephantech.co.jp/en/about/#contact>



Website



Contact